

Sn63/Pb37

MG Chemicals Sn63/Pb37 electronics grade solder wire is formulated from a blend of 63% tin and 37% lead. Made from non-recycled metal, it uses the eutectic tin-to-lead alloy ratio. Our flux core manufacturing process eliminates flux voids and irregular wire.

Being eutectic, it has no plastic range. This type is one of the easiest solders to work with because it offers a low melting temperature with a sharp melting/solidification point, which results in robust and reliable joints that are highly resistant to whisker formation. In most situations it flows better than the Sn60/Pb40, and is the preferred alloy for rework, component attachment and touch-up soldering for through-hole and surface mount applications. It meets or exceeds J-STD-004 and J-STD-006 specifications. This wire is available in a wide variety of sizes, diameters and gauges, allowing you to select a perfect fit for your specific needs.

Sn63/Pb37 NC Solder Wire

This wire features a no-clean, synthetically refined, splatter-proof resin flux core. It leaves a small amount of light opaque post-soldering residue that is non-conductive and non-corrosive, and won't cause electrical shorts.

The No Clean name refers to the fact that the board will not be adversely affected if it isn't cleaned. It does not mean there will be no residue.

- **No-clean formula**
- **Eutectic alloy**
- **Halide free**
- **Virtually non-splattering**
- **Melting point: 183 °C / 361 °F**

Sn63/Pb37 WS Solder Wire

This wire uses a water-soluble flux core. It offers great compatibility with all liquid water-soluble organic flux. It produces minimal splattering, and will not decompose and carbonize under prolonged heat. Cleaning flux residue requires only water rinsing or in-line cleaning after soldering.

- **Water soluble formula**
- **Low VOC**
- **Fast wetting and flowing action**
- **Melting point: 183 °C / 361 °F**

Cat. Number	Size		Diameter		Gauge	Flux %	Packaging
	g	oz	mm	in			
4860-18G	18 g	0.6 oz	1.01 mm	0.040"	19	2.2	Pack of 25
4865-227G	227 g	0.5 lb	0.63 mm	0.025"	22	2.2	Spool
4865-454G	454 g	1 lb	0.63 mm	0.025"	22	2.2	Spool
4866-227G	227 g	0.5 lb	1.01 mm	0.040"	20	2.2	Spool

Also available in flux core percentages 1.1% and 3.3%

Cat. Number	Size		Diameter		Gauge	Flux %	Packaging
	g	lb	mm	in			
4885WS-454G	454 g	1 lb	0.81 mm	0.032"	22	3.3	Spool

Also available in flux core percentages 1.1% and 2.2%

Sn63/Pb37 RA Solder Wire

This wire is complemented with an RA flux core, strong enough for excellent tarnish and oxide removal while producing bright shiny solder joints

RA Flux residues are non-corrosive and non-conductive, and therefore can be left on the board or cleaned with one of MG's flux removers. (See page 14)

- **Rosin activated flux core (RA)**
- **Eutectic alloy**
 - **Rapid wetting / Fast flowing**
 - **Consistent soldering**
 - **Non-corrosive**
- **Non-conductive flux residue**
- **Optional cleaning**
- **Standard Flux Core percentage at 2.2% ***
- **Melting point: 183 °C / 361 °F**

Cat. Number	Size		Diameter		Gauge	Flux %	Packaging
	g	lb	mm	in			
4880-18G	18 g	0.6 oz	0.81 mm	0.032"	22	2.2	Pack of 25
4884-227G	227 g	0.5 lb	0.63 mm	0.025"	23	2.2	Spool
4884-454G	454 g	1 lb	0.63 mm	0.025"	23	2.2	Spool
4885-227G	227 g	0.5 lb	0.81 mm	0.032"	22	2.2	Spool
4885-454G	454 g	1 lb	0.81 mm	0.032"	22	2.2	Spool
4886-227G	227 g	0.5 lb	1.01 mm	0.040"	20	2.2	Spool
4886-454G	454 g	1 lb	1.01 mm	0.040"	20	2.2	Spool
4887-227G	227 g	0.5 lb	1.27 mm	0.050"	18	2.2	Spool
4887-454G	454 g	1 lb	1.27 mm	0.050"	18	2.2	Spool
4888-227G	227 g	0.5 lb	1.57 mm	0.062"	16	2.2	Spool
4888-454G	454 g	1 lb	1.57 mm	0.062"	16	2.2	Spool

*Also available in Flux Core percentages 1.1% and 3.3%